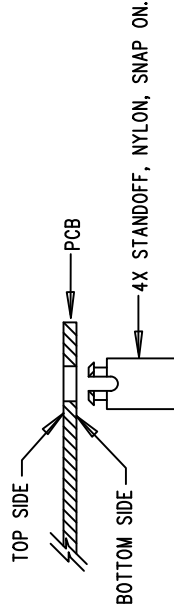



1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 LINEAR TECHNOLOGY 4630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408) 532-1900 www.linear.com LTT CONFIDENTIAL - FOR CUSTOMER USE ONLY
PCB DES.	HZ	
APP ENG.	JIAN L.	
TITLE: TOP ASSEMBLY DRAWING		
DUAL STEP-DOWN uMODULE REGULATOR		
WITH POWER SYSTEM MANAGEMENT		
SIZE	IC NO.	REV.
N/A	LTM4676EY/LTM4676AEY	1
N/A		DEM0 CIRCUIT 1811B-A/B
SCALE = NONE		FILENAME: DC1811B-1.PCB
		SHT 1 OF 2